

Silicon Carbide Market by Device (SiC Discrete Device, SiC Module), Wafer Size (Up to 150mm, >150mm), End-use Application (Automotive, Energy & Power, Industrial, Transportation), Material, Crystal Structure and Region - Global Forecast to 2029

Market Report | 2024-03-21 | 233 pages | MarketsandMarkets

AVAILABLE LICENSES:

- Single User \$4950.00
- Multi User \$6650.00
- Corporate License \$8150.00
- Enterprise Site License \$10000.00

Report description:

The silicon carbide market is projected to reach USD 17.2 billion by 2029 from USD 4.2 billion in 2024, at a CAGR of 32.6% from 2024 to 2029. The major factors driving the growth of silicon carbide market includes the increasing demand for power electronics, surging demand for renewable energy systems and growing number of initiatives and investments to encourage the adoption of SiC devices which is expected to provide several growth opportunities for market players in the silicon carbide market.

>150 mm segment is expected to witness the highest CAGR in the silicon carbide market during the forecast period

The >150 mm wafer size market is poised to exhibit the highest CAGR during the forecast period. These wafers are used across a spectrum of devices such as SiC MOSFETs and SiC modules, due to their 50% thinner profile as compared to standard silicon wafers. As these SiC wafers are engineered for high-volume production and applications that require elevated temperatures, they boast remarkable attributes such as high thermal conductivity, superior carrier mobility, and exceptional chemical stability. Therefore, >150 mm segment is expected to witness the highest CAGR during the forecast period.

Asia Pacific is expected to register the highest CAGR in the silicon carbide market during the forecast period

The presence of regional expanding scope of high-power applications presents significant revenue opportunities for power semiconductor devices in Asia Pacific, attracting numerous companies to commercialize silicon carbide semiconductor devices for various power applications. This expansion boosts the revenues of regional market players. Leading companies in the silicon carbide sector, such as ROHM Co., Ltd., Fuji Electric Co., Ltd., Renesas Electronics Corporation, Toshiba Corporation, and TanKeBlue Semiconductor Co. Ltd., are headquartered in Asia Pacific. Therefore, Asia Pacific is expected to register the highest CAGR in the silicon carbide market during the forecast period.

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

The break-up of profile of primary participants in the silicon carbide market-

-□By Company Type: Tier 1 - 35%, Tier 2 - 45%, Tier 3 - 20%

-□By Designation Type: C Level - 40%, Director Level - 30%, Others - 30%

-□By Region Type: North America - 30%, Europe - 20%, Asia Pacific - 40%, Rest of the World (RoW) - 10%

The major players of silicon carbide market are STMicroelectronics N.V. (Switzerland), Infineon Technologies AG (Germany), Semiconductor Components Industries, LLC (US), WOLFSPEED, INC. (US), and ROHM Co., Ltd. (Japan) among others.

Research Coverage

The report segments the silicon carbide market and forecasts its size based on device, wafer size, end-use application and region. The report also provides a comprehensive review of drivers, restraints, opportunities, and challenges influencing market growth. The report also covers qualitative aspects in addition to the quantitative aspects of the market.

Reasons to buy the report:

The report will help the market leaders/new entrants in this market with information on the closest approximate revenues for the overall silicon carbide market and related segments. This report will help stakeholders understand the competitive landscape and gain more insights to strengthen their position in the market and plan suitable go-to-market strategies. The report also helps stakeholders understand the pulse of the market and provides them with information on key market drivers, restraints, opportunities, and challenges.

The report provides insights on the following pointers:

-□Analysis of key drivers (increasing demand for power electronics, surging demand for renewable energy systems, growing number of initiatives and investments to encourage the adoption of SiC devices), restraints (high efficacy of alternative technologies for power electronics), opportunities (ongoing advancements towards the quality of SiC substrate and epitaxy), and challenges (material defects and designing and packaging issues in SiC devices) influencing the growth of the silicon carbide market.

-□Product Development/Innovation: Detailed insights on upcoming technologies, research & development activities, and new product launches in the silicon carbide market.

-□Market Development: Comprehensive information about lucrative markets - the report analyses the silicon carbide market across varied regions.

-□Market Diversification: Exhaustive information about new products, untapped geographies, recent developments, and investments in the silicon carbide market

-□Competitive Assessment: In-depth assessment of market shares, growth strategies and product offerings of leading players like STMicroelectronics N.V. (Switzerland), Infineon Technologies AG (Germany), Semiconductor Components Industries, LLC (US), WOLFSPEED, INC. (US), and ROHM Co., Ltd. (Japan)

Table of Contents:

| | |
|---|----|
| 1□INTRODUCTION□ | 28 |
| 1.1□STUDY OBJECTIVES□ | 28 |
| 1.2□MARKET DEFINITION□ | 28 |
| 1.3□STUDY SCOPE□ | 29 |
| 1.3.1□INCLUSIONS AND EXCLUSIONS□ | 29 |
| 1.3.1.1□Company: Inclusions and exclusions□ | 29 |
| 1.3.1.2□Device: Inclusions and exclusions□ | 29 |

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

| | | |
|-----------|---|----|
| 1.3.1.3 | Wafer size: Inclusions and exclusions | 29 |
| 1.3.1.4 | Vertical: Inclusions and exclusions | 29 |
| 1.3.1.5 | Region: Inclusions and exclusions | 30 |
| 1.3.2 | MARKETS COVERED | 30 |
| FIGURE 1 | SIC MARKET SEGMENTATION | 30 |
| 1.3.3 | REGIONAL SCOPE | 31 |
| 1.3.4 | YEARS CONSIDERED | 31 |
| 1.4 | CURRENCY CONSIDERED | 31 |
| 1.5 | UNITS CONSIDERED | 31 |
| 1.6 | LIMITATIONS | 32 |
| 1.7 | STAKEHOLDERS | 32 |
| 1.8 | SUMMARY OF CHANGES | 32 |
| 1.9 | IMPACT OF RECESSION | 32 |
| 2 | RESEARCH METHODOLOGY | 33 |
| 2.1 | RESEARCH DATA | 33 |
| FIGURE 2 | SIC MARKET: RESEARCH DESIGN | 33 |
| 2.1.1 | SECONDARY DATA | 34 |
| 2.1.1.1 | Major secondary sources | 34 |
| 2.1.1.2 | Key data from secondary sources | 35 |
| 2.1.2 | PRIMARY DATA | 35 |
| 2.1.2.1 | List of primary interview participants | 36 |
| 2.1.2.2 | Breakdown of primaries | 36 |
| 2.1.2.3 | Key industry insights | 36 |
| 2.1.2.4 | Key data from primary sources | 37 |
| 2.1.3 | SECONDARY AND PRIMARY RESEARCH | 38 |
| 2.2 | MARKET SIZE ESTIMATION | 39 |
| FIGURE 3 | MARKET SIZE ESTIMATION: SUPPLY-SIDE ANALYSIS | 39 |
| 2.2.1 | BOTTOM-UP APPROACH | 39 |
| 2.2.1.1 | Approach to estimate market size using bottom-up analysis (demand side) | 39 |
| FIGURE 4 | MARKET SIZE ESTIMATION METHODOLOGY: BOTTOM-UP APPROACH | 40 |
| 2.2.2 | TOP-DOWN APPROACH | 40 |
| 2.2.2.1 | Approach to estimate market size using top-down analysis (supply side) | 40 |
| FIGURE 5 | MARKET SIZE ESTIMATION METHODOLOGY: TOP-DOWN APPROACH | 41 |
| 2.3 | FACTOR ANALYSIS | 41 |
| 2.3.1 | SUPPLY-SIDE ANALYSIS | 41 |
| FIGURE 6 | MARKET SIZE ESTIMATION METHODOLOGY: SUPPLY-SIDE ANALYSIS (APPROACH 1) | 41 |
| FIGURE 7 | MARKET SIZE ESTIMATION METHODOLOGY: SUPPLY-SIDE ANALYSIS (APPROACH 2) | 42 |
| 2.4 | MARKET GROWTH ASSUMPTIONS | 42 |
| TABLE 1 | SIC MARKET: GROWTH ASSUMPTIONS | 42 |
| 2.5 | PARAMETERS CONSIDERED TO ANALYZE IMPACT OF RECESSION ON SIC MARKET | 43 |
| 2.6 | DATA TRIANGULATION | 44 |
| FIGURE 8 | DATA TRIANGULATION | 44 |
| 2.7 | RESEARCH ASSUMPTIONS | 45 |
| 2.8 | RISK ASSESSMENT | 45 |
| 3 | EXECUTIVE SUMMARY | 46 |
| FIGURE 9 | SIC MARKET: GLOBAL SNAPSHOT | 47 |
| FIGURE 10 | SIC MODULE SEGMENT TO REGISTER HIGHEST CAGR DURING FORECAST PERIOD | 47 |

| | | |
|-----------|--|----|
| FIGURE 11 | >150 MM SEGMENT TO RECORD HIGHER GROWTH RATE DURING FORECAST PERIOD | 48 |
| FIGURE 12 | AUTOMOTIVE SEGMENT TO ACCOUNT FOR LARGEST MARKET SHARE IN 2029 | 48 |
| FIGURE 13 | ASIA PACIFIC TO DOMINATE MARKET DURING FORECAST PERIOD | 49 |
| 4 | PREMIUM INSIGHTS | 50 |
| 4.1 | ATTRACTIVE OPPORTUNITIES FOR PLAYERS IN SiC MARKET | 50 |
| FIGURE 14 | GROWING DEMAND FOR EVs AND RENEWABLE ENERGY SYSTEMS TO DRIVE MARKET | 50 |
| 4.2 | SiC MARKET, BY VERTICAL | 51 |
| FIGURE 15 | AUTOMOTIVE SEGMENT TO ACCOUNT FOR LARGEST MARKET SHARE DURING IN 2024 | 51 |
| 4.3 | SiC MARKET, BY DEVICE | 51 |
| FIGURE 16 | SiC MODULES SEGMENT TO HOLD LARGEST MARKET SHARE IN 2029 | 51 |
| 4.4 | SiC MARKET, BY WAFER SIZE | 52 |
| FIGURE 17 | UP TO 150 MM SEGMENT TO SECURE LARGER MARKET SHARE IN 2029 | 52 |
| 4.5 | SiC MARKET IN ASIA PACIFIC, BY VERTICAL AND COUNTRY, 2024 | 52 |
| FIGURE 18 | AUTOMOTIVE SEGMENT AND CHINA TO ACCOUNT FOR LARGEST ASIA PACIFIC MARKET SHARES | 52 |
| 5 | MARKET OVERVIEW | 53 |
| 5.1 | INTRODUCTION | 53 |
| 5.2 | MARKET DYNAMICS | 53 |
| FIGURE 19 | SiC MARKET: DRIVERS, RESTRAINTS, OPPORTUNITIES, AND CHALLENGES | 54 |
| 5.2.1 | DRIVERS | 54 |
| 5.2.1.1 | Growing deployment of SiC devices in EVs | 54 |
| FIGURE 20 | GLOBAL SALES OF EVs, 2019-2021 | 55 |
| 5.2.1.2 | Increasing demand for power electronics | 55 |
| 5.2.1.3 | Rising demand for renewable energy systems | 55 |
| FIGURE 21 | GLOBAL SHARE OF RENEWABLE ENERGY GENERATION, 2022-2028 | 56 |
| 5.2.1.4 | Increasing initiatives and investments in SiC devices | 56 |
| FIGURE 22 | IMPACT ANALYSIS OF DRIVERS ON SiC MARKET | 57 |
| 5.2.2 | RESTRAINTS | 58 |
| 5.2.2.1 | High efficacy of alternative technologies for power electronics | 58 |
| 5.2.2.2 | High cost of SiC devices | 58 |
| FIGURE 23 | IMPACT ANALYSIS OF RESTRAINTS ON SiC MARKET | 59 |
| 5.2.3 | OPPORTUNITIES | 59 |
| 5.2.3.1 | Growing adoption of SiC devices in telecommunications industry | 59 |
| 5.2.3.2 | Ongoing quality enhancements of SiC substrates and epitaxy processes | 60 |
| FIGURE 24 | IMPACT ANALYSIS OF OPPORTUNITIES ON SiC MARKET | 60 |
| 5.2.4 | CHALLENGES | 61 |
| 5.2.4.1 | Material defects and designing and packaging issues in SiC devices | 61 |
| FIGURE 25 | IMPACT ANALYSIS OF CHALLENGES ON SiC MARKET | 61 |
| 5.3 | SUPPLY CHAIN ANALYSIS | 62 |
| FIGURE 26 | SiC MARKET: SUPPLY CHAIN ANALYSIS | 62 |
| TABLE 2 | SiC MARKET: SUPPLY CHAIN ANALYSIS | 63 |
| 5.4 | ECOSYSTEM ANALYSIS | 64 |
| FIGURE 27 | SiC MARKET: ECOSYSTEM ANALYSIS | 64 |
| 5.5 | INVESTMENT AND FUNDING SCENARIO | 65 |
| FIGURE 28 | INVESTMENT AND FUNDING SCENARIO, 2019-2023 | 65 |
| 5.6 | TRENDS/DISRUPTIONS IMPACTING CUSTOMERS' BUSINESSES | 65 |
| FIGURE 29 | TRENDS/DISRUPTIONS IMPACTING CUSTOMERS' BUSINESSES | 65 |
| 5.7 | TECHNOLOGY ANALYSIS | 66 |

| | | |
|-----------|--|----|
| 5.7.1 | KEY TECHNOLOGIES | 66 |
| 5.7.1.1 | 4th Gen SiC | 66 |
| 5.7.1.2 | 8-inch SiC wafer | 66 |
| 5.7.2 | COMPLEMENTARY TECHNOLOGIES | 66 |
| 5.7.2.1 | SiC-on-insulator (SiCOI) | 66 |
| 5.7.2.2 | SiC-on-GaN | 67 |
| 5.7.3 | ADJACENT TECHNOLOGIES | 67 |
| 5.7.3.1 | Gallium nitride (GaN) | 67 |
| 5.7.3.2 | Indium gallium nitride (InGaN) | 67 |
| 5.8 | PRICING ANALYSIS | 68 |
| 5.8.1 | AVERAGE SELLING PRICE OF PRODUCTS OFFERED BY KEY PLAYERS | 68 |
| FIGURE 30 | AVERAGE SELLING PRICE OF PRODUCTS OFFERED BY KEY PLAYERS | 68 |
| TABLE 3 | AVERAGE SELLING PRICE OF SIC MOSFETS, SIC DIODES, AND SIC MODULES OFFERED BY KEY PLAYERS | 68 |
| 5.8.2 | AVERAGE SELLING PRICE TREND OF SIC DEVICES, BY TYPE | 69 |
| FIGURE 31 | AVERAGE SELLING PRICE TREND OF SIC DEVICES, BY TYPE | 69 |
| 5.8.3 | AVERAGE SELLING PRICE TREND OF SIC DEVICES, BY REGION | 69 |
| FIGURE 32 | AVERAGE SELLING PRICE TREND OF SIC MOSFETS, BY REGION | 69 |
| 5.9 | KEY STAKEHOLDERS AND BUYING CRITERIA | 70 |
| 5.9.1 | KEY STAKEHOLDERS IN BUYING PROCESS | 70 |
| FIGURE 33 | INFLUENCE OF STAKEHOLDERS ON BUYING PROCESS OF TOP THREE VERTICALS | 70 |
| TABLE 4 | INFLUENCE OF STAKEHOLDERS ON BUYING PROCESS OF TOP THREE VERTICALS | 70 |
| 5.9.2 | BUYING CRITERIA | 71 |
| FIGURE 34 | KEY BUYING CRITERIA OF TOP THREE VERTICALS | 71 |
| TABLE 5 | KEY BUYING CRITERIA FOR TOP THREE VERTICALS | 71 |
| 5.10 | PORTER'S FIVE FORCES ANALYSIS | 72 |
| TABLE 6 | SIC MARKET: PORTER'S FIVE FORCES ANALYSIS | 72 |
| FIGURE 35 | SIC MARKET: PORTER'S FIVE FORCES ANALYSIS, 2023 | 72 |
| 5.10.1 | THREAT OF NEW ENTRANTS | 73 |
| 5.10.2 | THREAT OF SUBSTITUTES | 73 |
| 5.10.3 | BARGAINING POWER OF SUPPLIERS | 73 |
| 5.10.4 | BARGAINING POWER OF BUYERS | 73 |
| 5.10.5 | INTENSITY OF COMPETITIVE RIVALRY | 73 |
| 5.11 | CASE STUDY ANALYSIS | 74 |
| 5.11.1 | JAGUAR LAND ROVER INTEGRATED WOLFSPEED'S SIC DEVICES INTO EVS TO ENHANCE POWERTRAIN EFFICIENCY AND EXTEND DRIVING RANGE | 74 |
| 5.11.2 | BORGWARNER INC. DELIVERED INNOVATIVE AND SUSTAINABLE MOBILITY SOLUTIONS THROUGH INTEGRATION OF STMICROELECTRONICS' SIC MOSFETS | 74 |
| 5.11.3 | AMPT'S DC STRING ENHANCED OPTIMIZERS BY INTEGRATING ONSEMI'S SIC MOSFET | 74 |
| 5.11.4 | DRIVING PERFORMANCE AND COST EFFICIENCY OF MERSEN'S SIC POWER STACK REFERENCE DESIGN | 75 |
| 5.12 | TRADE ANALYSIS | 75 |
| 5.12.1 | IMPORT SCENARIO | 75 |
| TABLE 7 | IMPORT DATA FOR HS CODE 284920-COMPLIANT PRODUCTS, BY COUNTRY, 2018-2022 (USD MILLION) | 75 |
| FIGURE 36 | IMPORT DATA FOR HS CODE 284920-COMPLIANT PRODUCTS, BY COUNTRY, 2018-2022 | 76 |
| 5.12.2 | EXPORT SCENARIO | 76 |
| TABLE 8 | EXPORT DATA FOR HS CODE 284920- COMPLIANT PRODUCTS, BY COUNTRY, 2018-2022 (USD MILLION) | 76 |
| FIGURE 37 | EXPORT DATA FOR HS CODE 284920-COMPLIANT PRODUCTS, BY COUNTRY, 2018-2022 | 77 |
| 5.13 | PATENT ANALYSIS | 77 |

| | | |
|-----------|--|----|
| TABLE 9 | NUMBER OF PATENTS GRANTED, JANUARY 2013-DECEMBER 2023 | 77 |
| FIGURE 38 | NUMBER OF PATENTS GRANTED, 2013-2023 | 77 |
| FIGURE 39 | TOP 10 COMPANIES WITH HIGHEST NUMBER OF GRANTED PATENTS, 2013-2023 | 78 |
| TABLE 10 | TOP 20 PATENT OWNERS IN LAST 10 YEARS | 78 |
| TABLE 11 | MAJOR PATENTS RELATED TO SIC DEVICES | 79 |
| 5.14 | REGULATORY LANDSCAPE | 80 |
| 5.14.1 | GLOBAL STANDARDS | 80 |
| 5.14.2 | GOVERNMENT REGULATIONS | 80 |
| 5.14.2.1 | Asia Pacific | 80 |
| 5.14.2.2 | North America | 80 |
| 5.14.2.3 | Europe | 81 |
| 5.15 | KEY CONFERENCES AND EVENTS, 2024-2025 | 82 |
| TABLE 12 | SIC MARKET: KEY CONFERENCES AND EVENTS, 2024-2025 | 82 |
| 6 | SIC MARKET, BY DEVICE | 83 |
| 6.1 | INTRODUCTION | 84 |
| FIGURE 40 | SIC MODULES SEGMENT TO REGISTER HIGHEST CAGR DURING FORECAST PERIOD | 84 |
| TABLE 13 | SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 84 |
| TABLE 14 | SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 84 |
| 6.2 | SIC DISCRETE DEVICES | 85 |
| 6.2.1 | INCREASING APPLICATIONS IN EVS AND 5G INFRASTRUCTURE TO DRIVE MARKET | 85 |
| 6.2.2 | SIC DIODES | 85 |
| 6.2.2.1 | Higher electrical and thermal conductivity than silicon variants to boost demand | 85 |
| 6.2.3 | SIC MOSFETS | 86 |
| 6.2.3.1 | Ability to function as power-switching transistors to boost demand | 86 |
| TABLE 15 | SIC DISCRETE DEVICES: SIC MARKET, BY TYPE, 2020-2023 (USD MILLION) | 86 |
| TABLE 16 | SIC DISCRETE DEVICES: SIC MARKET, BY TYPE, 2024-2029 (USD MILLION) | 86 |
| TABLE 17 | SIC DISCRETE DEVICES: SIC MARKET, BY TYPE, 2020-2023 (MILLION UNITS) | 87 |
| TABLE 18 | SIC DISCRETE DEVICES: SIC MARKET, BY TYPE, 2024-2029 (MILLION UNITS) | 87 |
| TABLE 19 | SIC DISCRETE DEVICES: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 87 |
| TABLE 20 | SIC DISCRETE DEVICES: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 87 |
| TABLE 21 | SIC DISCRETE DEVICES: SIC MARKET IN ASIA PACIFIC, BY COUNTRY, 2020-2023 (USD MILLION) | 88 |
| TABLE 22 | SIC DISCRETE DEVICES: SIC MARKET IN ASIA PACIFIC, BY COUNTRY, 2024-2029 (USD MILLION) | 88 |
| TABLE 23 | SIC DISCRETE DEVICES: SIC MARKET IN EUROPE, BY COUNTRY, 2020-2023 (USD MILLION) | 88 |
| TABLE 24 | SIC DISCRETE DEVICES: SIC MARKET IN EUROPE, BY COUNTRY, 2024-2029 (USD MILLION) | 89 |
| TABLE 25 | SIC DISCRETE DEVICES: SIC MARKET IN NORTH AMERICA, BY COUNTRY, 2020-2023 (USD MILLION) | 89 |
| TABLE 26 | SIC DISCRETE DEVICES: SIC MARKET IN NORTH AMERICA, BY COUNTRY, 2024-2029 (USD MILLION) | 89 |
| TABLE 27 | SIC DISCRETE DEVICES: SIC MARKET IN ROW, BY REGION, 2020-2023 (USD MILLION) | 89 |
| TABLE 28 | SIC DISCRETE DEVICES: SIC MARKET IN ROW, BY REGION, 2024-2029 (USD MILLION) | 90 |
| 6.3 | SIC MODULES | 90 |
| 6.3.1 | REDUCED NEED FOR PASSIVE COMPONENTS AND SMALL SYSTEM FOOTPRINT TO ACCELERATE DEMAND | 90 |
| FIGURE 41 | ASIA PACIFIC TO RECORD HIGHEST CAGR DURING FORECAST PERIOD | 90 |
| TABLE 29 | SIC MODULES: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 91 |
| TABLE 30 | SIC MODULES: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 91 |
| TABLE 31 | SIC MODULES: SIC MARKET IN ASIA PACIFIC, BY COUNTRY, 2020-2023 (USD MILLION) | 91 |
| TABLE 32 | SIC MODULES: SIC MARKET IN ASIA PACIFIC, BY COUNTRY, 2024-2029 (USD MILLION) | 91 |
| TABLE 33 | SIC MODULES: SIC MARKET IN EUROPE, BY COUNTRY, 2020-2023 (USD MILLION) | 92 |
| TABLE 34 | SIC MODULES: SIC MARKET IN EUROPE, BY COUNTRY, 2024-2029 (USD MILLION) | 92 |

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

| | | |
|-----------|---|-----|
| TABLE 35 | SIC MODULES: SIC MARKET IN NORTH AMERICA, BY COUNTRY, 2020-2023 (USD MILLION) | 92 |
| TABLE 36 | SIC MODULES: SIC MARKET IN NORTH AMERICA, BY COUNTRY, 2024-2029 (USD MILLION) | 92 |
| TABLE 37 | SIC MODULES: SIC MARKET IN ROW, BY REGION, 2020-2023 (USD MILLION) | 93 |
| TABLE 38 | SIC MODULES: SIC MARKET IN ROW, BY REGION, 2024-2029 (USD MILLION) | 93 |
| 7 | SIC MARKET, BY WAFER SIZE | 94 |
| 7.1 | INTRODUCTION | 95 |
| FIGURE 42 | >150 MM SEGMENT TO REGISTER HIGHER CAGR DURING FORECAST PERIOD | 95 |
| TABLE 39 | SIC MARKET, BY WAFER SIZE, 2020-2023 (USD MILLION) | 95 |
| TABLE 40 | SIC MARKET, BY WAFER SIZE, 2024-2029 (USD MILLION) | 95 |
| 7.2 | UP TO 150 MM | 96 |
| 7.2.1 | GROWING DEPLOYMENT IN HIGH-FREQUENCY DEVICES TO FUEL MARKET GROWTH | 96 |
| 7.3 | >150 MM | 96 |
| 7.3.1 | ABILITY TO OFFER LARGE NUMBER OF DEVICES ON SINGLE WAFER TO DRIVE MARKET | 96 |
| 8 | CRYSTAL STRUCTURES OF SIC DEVICES | 97 |
| 8.1 | INTRODUCTION | 97 |
| 8.2 | ZINC BLENDE (3C-SIC) | 97 |
| 8.3 | WURTZITE (4H-SIC) | 98 |
| 8.4 | WURTZITE (6H-SIC) | 98 |
| 8.5 | RHOMBOHEDRAL (15R-SIC) | 98 |
| 9 | SIC MATERIAL TYPES | 99 |
| 9.1 | INTRODUCTION | 99 |
| 9.2 | GREEN SIC | 99 |
| 9.3 | BLACK SIC | 99 |
| 10 | SIC MARKET, BY VERTICAL | 100 |
| 10.1 | INTRODUCTION | 101 |
| FIGURE 43 | AUTOMOTIVE SEGMENT TO DOMINATE MARKET DURING FORECAST PERIOD | 101 |
| TABLE 41 | SIC MARKET, BY VERTICAL, 2020-2023 (USD MILLION) | 101 |
| TABLE 42 | SIC MARKET, BY VERTICAL, 2024-2029 (USD MILLION) | 102 |
| 10.2 | AUTOMOTIVE | 102 |
| 10.2.1 | GROWING DEMAND FOR HIGH-PERFORMING OPTO-SEMICONDUCTOR DEVICES TO BOOST DEMAND | 102 |
| FIGURE 44 | ASIA PACIFIC TO SECURE LARGEST MARKET SHARE IN 2029 | 103 |
| TABLE 43 | AUTOMOTIVE: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 103 |
| TABLE 44 | AUTOMOTIVE: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 103 |
| 10.3 | ENERGY & POWER | 104 |
| 10.3.1 | RAPID ADOPTION IN RENEWABLE ENERGY SYSTEMS TO ACCELERATE DEMAND | 104 |
| TABLE 45 | ENERGY & POWER: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 104 |
| TABLE 46 | ENERGY & POWER: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 105 |
| 10.4 | INDUSTRIAL | 105 |
| 10.4.1 | GROWING USE IN ROBOTICS TO BOOST DEMAND | 105 |
| TABLE 47 | INDUSTRIAL: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 105 |
| TABLE 48 | INDUSTRIAL: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 106 |
| 10.5 | TRANSPORTATION | 106 |
| 10.5.1 | EASE OF HEAT DISSIPATION DUE TO HIGH THERMAL CONDUCTIVITY TO DRIVE MARKET | 106 |
| 10.5.2 | CHARGING STATIONS | 106 |
| 10.5.2.1 | Fast charging with high power density to drive market | 106 |
| 10.5.3 | RAILS | 107 |
| 10.5.3.1 | Reduced power losses within rail modules to accelerate demand | 107 |

| | | |
|-----------|--|-----|
| TABLE 49 | TRANSPORTATION: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 107 |
| TABLE 50 | TRANSPORTATION: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 107 |
| 10.6 | TELECOMMUNICATIONS | 108 |
| 10.6.1 | RIISING ADOPTION IN 5G WIRELESS COMMUNICATION TO DRIVE MARKET | 108 |
| TABLE 51 | TELECOMMUNICATIONS: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 108 |
| TABLE 52 | TELECOMMUNICATIONS: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 108 |
| 10.7 | OTHERS | 109 |
| TABLE 53 | OTHERS: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 109 |
| TABLE 54 | OTHERS: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 109 |
| 11 | SIC MARKET, BY REGION | 110 |
| 11.1 | INTRODUCTION | 111 |
| FIGURE 45 | CHINA TO REGISTER HIGHEST CAGR IN GLOBAL SIC MARKET DURING FORECAST PERIOD | 111 |
| TABLE 55 | SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 111 |
| TABLE 56 | SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 112 |
| 11.2 | NORTH AMERICA | 112 |
| 11.2.1 | NORTH AMERICA: RECESSION IMPACT | 112 |
| FIGURE 46 | NORTH AMERICA: SIC MARKET SNAPSHOT | 113 |
| TABLE 57 | NORTH AMERICA: SIC MARKET, BY COUNTRY, 2020-2023 (USD MILLION) | 113 |
| TABLE 58 | NORTH AMERICA: SIC MARKET, BY COUNTRY, 2024-2029 (USD MILLION) | 114 |
| TABLE 59 | NORTH AMERICA: SIC MARKET, BY VERTICAL, 2020-2023 (USD MILLION) | 114 |
| TABLE 60 | NORTH AMERICA: SIC MARKET, BY VERTICAL, 2024-2029 (USD MILLION) | 114 |
| TABLE 61 | NORTH AMERICA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 115 |
| TABLE 62 | NORTH AMERICA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 115 |
| 11.2.2 | US | 115 |
| 11.2.2.1 | Growing demand for EVs and charging stations to drive market | 115 |
| TABLE 63 | US: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 116 |
| TABLE 64 | US: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 116 |
| 11.2.3 | CANADA | 116 |
| 11.2.3.1 | Government initiatives toward clean technology to increase demand for EVs and drive market | 116 |
| TABLE 65 | CANADA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 116 |
| TABLE 66 | CANADA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 117 |
| 11.2.4 | MEXICO | 117 |
| 11.2.4.1 | Increasing number of manufacturing facilities and expanding distribution network of SiC device manufacturers to drive market | 117 |
| TABLE 67 | MEXICO: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 117 |
| TABLE 68 | MEXICO: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 117 |
| 11.3 | EUROPE | 118 |
| 11.3.1 | EUROPE: RECESSION IMPACT | 118 |
| FIGURE 47 | EUROPE: SIC MARKET SNAPSHOT | 119 |
| TABLE 69 | EUROPE: SIC MARKET, BY COUNTRY, 2020-2023 (USD MILLION) | 119 |
| TABLE 70 | EUROPE: SIC MARKET, BY COUNTRY, 2024-2029 (USD MILLION) | 120 |
| TABLE 71 | EUROPE: SIC MARKET, BY VERTICAL, 2020-2023 (USD MILLION) | 120 |
| TABLE 72 | EUROPE: SIC MARKET, BY VERTICAL, 2024-2029 (USD MILLION) | 120 |
| TABLE 73 | EUROPE: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 120 |
| TABLE 74 | EUROPE: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 121 |
| 11.3.2 | UK | 121 |
| 11.3.2.1 | Growing adoption of connected and autonomous vehicles (CAVs) to drive market | 121 |

| | | |
|-----------|--|-----|
| TABLE 75 | UK: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 121 |
| TABLE 76 | UK: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 122 |
| 11.3.3 | GERMANY | 122 |
| 11.3.3.1 | Increasing applications in power supplies, EV motor drives, and charging stations to drive market | 122 |
| TABLE 77 | GERMANY: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 122 |
| TABLE 78 | GERMANY: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 122 |
| 11.3.4 | FRANCE | 123 |
| 11.3.4.1 | Surging adoption of renewable energy systems to drive market | 123 |
| TABLE 79 | FRANCE: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 123 |
| TABLE 80 | FRANCE: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 123 |
| 11.3.5 | REST OF EUROPE | 124 |
| TABLE 81 | REST OF EUROPE: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 124 |
| TABLE 82 | REST OF EUROPE: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 124 |
| 11.4 | ASIA PACIFIC | 125 |
| 11.4.1 | ASIA PACIFIC: RECESSION IMPACT | 125 |
| FIGURE 48 | ASIA PACIFIC: SIC MARKET SNAPSHOT | 126 |
| TABLE 83 | ASIA PACIFIC: SIC MARKET, BY COUNTRY, 2020-2023 (USD MILLION) | 126 |
| TABLE 84 | ASIA PACIFIC: SIC MARKET, BY COUNTRY, 2024-2029 (USD MILLION) | 127 |
| TABLE 85 | ASIA PACIFIC: SIC MARKET, BY VERTICAL, 2020-2023 (USD MILLION) | 127 |
| TABLE 86 | ASIA PACIFIC: SIC MARKET, BY VERTICAL, 2024-2029 (USD MILLION) | 127 |
| TABLE 87 | ASIA PACIFIC: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 128 |
| TABLE 88 | ASIA PACIFIC: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 128 |
| 11.4.2 | CHINA | 128 |
| 11.4.2.1 | Thriving power electronics industry to fuel market growth | 128 |
| TABLE 89 | CHINA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 129 |
| TABLE 90 | CHINA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 129 |
| 11.4.3 | JAPAN | 129 |
| 11.4.3.1 | Increased R&D activities in industrial, automotive, and telecommunications verticals to boost demand | 129 |
| TABLE 91 | JAPAN: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 130 |
| TABLE 92 | JAPAN: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 130 |
| 11.4.4 | SOUTH KOREA | 130 |
| 11.4.4.1 | Growing demand for consumer electronics to drive adoption | 130 |
| TABLE 93 | SOUTH KOREA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 131 |
| TABLE 94 | SOUTH KOREA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 131 |
| 11.4.5 | REST OF ASIA PACIFIC | 131 |
| TABLE 95 | REST OF ASIA PACIFIC: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 132 |
| TABLE 96 | REST OF ASIA PACIFIC: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 132 |
| 11.5 | ROW | 132 |
| 11.5.1 | ROW: RECESSION IMPACT | 132 |
| TABLE 97 | ROW: SIC MARKET, BY REGION, 2020-2023 (USD MILLION) | 133 |
| TABLE 98 | ROW: SIC MARKET, BY REGION, 2024-2029 (USD MILLION) | 133 |
| TABLE 99 | ROW: SIC MARKET, BY VERTICAL, 2020-2023 (USD MILLION) | 133 |
| TABLE 100 | ROW: SIC MARKET, BY VERTICAL, 2024-2029 (USD MILLION) | 133 |
| TABLE 101 | ROW: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION) | 134 |
| TABLE 102 | ROW: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION) | 134 |
| 11.5.2 | MIDDLE EAST & AFRICA | 134 |
| 11.5.2.1 | Increasing adoption in renewable energy systems to drive market | 134 |

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

11.5.2.2GCC Countries134

11.5.2.2.1Increasing investments in semiconductor industry to boost demand134

11.5.2.3Rest of Middle East & Africa135

TABLE 103MIDDLE EAST & AFRICA: SIC MARKET, BY REGION, 2020-2023 (USD MILLION)135

TABLE 104MIDDLE EAST & AFRICA: SIC MARKET, BY REGION, 2024-2029 (USD MILLION)135

TABLE 105MIDDLE EAST & AFRICA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION)135

TABLE 106MIDDLE EAST & AFRICA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION)136

11.5.3SOUTH AMERICA136

11.5.3.1Expanding telecommunications industry to boost demand136

TABLE 107SOUTH AMERICA: SIC MARKET, BY DEVICE, 2020-2023 (USD MILLION)136

TABLE 108SOUTH AMERICA: SIC MARKET, BY DEVICE, 2024-2029 (USD MILLION)136

12COMPETITIVE LANDSCAPE137

12.1OVERVIEW137

12.2STRATEGIES ADOPTED BY KEY PLAYERS, 2020-2024137

TABLE 109OVERVIEW OF STRATEGIES ADOPTED BY KEY PLAYERS, 2020-2024137

FIGURE 49ORGANIC/INORGANIC STRATEGIES ADOPTED BY KEY PLAYERS, 2020-2024138

12.3MARKET SHARE ANALYSIS, 2023139

FIGURE 50SIC MARKET: MARKET SHARE ANALYSIS, 2023139

TABLE 110SIC MARKET: DEGREE OF COMPETITION, 2023140

12.4COMPANY VALUATION AND FINANCIAL METRICS141

FIGURE 51SIC MARKET: COMPANY VALUATION, 2023141

FIGURE 52FINANCIAL METRICS (EV/EBITDA), 2024142

12.5BRAND/PRODUCT COMPARISON142

FIGURE 53SIC MARKET: BRAND/PRODUCT COMPARISON142

12.6REVENUE ANALYSIS OF FIVE KEY PLAYERS, 2019-2023143

FIGURE 54SIC MARKET: REVENUE ANALYSIS OF FIVE KEY PLAYERS, 2019-2023 (USD BILLION)143

12.7COMPANY EVALUATION MATRIX: KEY PLAYERS, 2023144

12.7.1STARS144

12.7.2EMERGING LEADERS144

12.7.3PERVASIVE PLAYERS144

12.7.4PARTICIPANTS144

FIGURE 55SIC MARKET: COMPANY EVALUATION MATRIX: KEY PLAYERS, 2023145

12.7.5COMPANY FOOTPRINT: KEY PLAYERS, 2023146

12.7.5.1Overall footprint146

FIGURE 56OVERALL FOOTPRINT146

12.7.5.2Device footprint147

TABLE 111SIC MARKET: DEVICE FOOTPRINT147

12.7.5.3Wafersize footprint148

TABLE 112SIC MARKET: WAFER SIZE FOOTPRINT148

12.7.5.4Application footprint149

TABLE 113SIC MARKET: APPLICATION FOOTPRINT149

12.7.5.5Region footprint150

TABLE 114SIC MARKET: REGION FOOTPRINT150

12.8COMPANY EVALUATION MATRIX: STARTUPS/SMES, 2023151

12.8.1PROGRESSIVE COMPANIES151

12.8.2RESPONSIVE COMPANIES151

12.8.3DYNAMIC COMPANIES151

| | | |
|-----------|--|-----|
| 12.8.4 | STARTING BLOCKS | 151 |
| FIGURE 57 | SIC MARKET: COMPANY EVALUATION MATRIX: STARTUPS/SMES, 2023 | 152 |
| 12.8.5 | COMPETITIVE BENCHMARKING: STARTUPS/SMES, 2023 | 153 |
| 12.8.5.1 | List of key startups/SMEs | 153 |
| TABLE 115 | SIC MARKET: LIST OF KEY STARTUPS/SMES, 2023 | 153 |
| 12.8.6 | COMPANY FOOTPRINT: STARTUPS/SMES FOOTPRINT | 154 |
| 12.8.6.1 | Device footprint | 154 |
| TABLE 116 | SIC MARKET: STARTUP/SME DEVICE FOOTPRINT | 154 |
| 12.8.6.2 | Wafer size footprint | 154 |
| TABLE 117 | SIC MARKET: STARTUP/SME WAFER SIZE FOOTPRINT | 154 |
| 12.8.6.3 | Application footprint | 155 |
| TABLE 118 | SIC MARKET: STARTUP/SME APPLICATION FOOTPRINT | 155 |
| 12.8.6.4 | Region footprint | 155 |
| TABLE 119 | SIC MARKET: STARTUP/SME REGION FOOTPRINT | 155 |
| 12.9 | COMPETITIVE SCENARIOS AND TRENDS | 156 |
| 12.9.1 | PRODUCT LAUNCHES | 156 |
| TABLE 120 | SIC MARKET: PRODUCT LAUNCHES, JUNE 2020-FEBRUARY 2024 | 156 |
| 12.9.2 | DEALS | 161 |
| TABLE 121 | SIC MARKET: DEALS, JUNE 2020-FEBRUARY 2024 | 161 |
| 12.9.3 | OTHERS | 169 |
| TABLE 122 | SIC MARKET: OTHERS, JUNE 2020 -FEBRUARY 2024 | 169 |
| ? | | |
| 13 | COMPANY PROFILES | 171 |
| 13.1 | INTRODUCTION | 171 |
| 13.2 | KEY PLAYERS | 171 |
| | (Business Overview, Products/Services/Solutions Offered, MnM View, Key Strengths and Right to Win, Strategic Choices Made, Weaknesses and Competitive Threats, Recent Developments)* | |
| 13.2.1 | STMICROELECTRONICS | 171 |
| TABLE 123 | STMICROELECTRONICS: COMPANY OVERVIEW | 172 |
| FIGURE 58 | STMICROELECTRONICS: COMPANY SNAPSHOT | 172 |
| TABLE 124 | STMICROELECTRONICS: PRODUCTS/SOLUTIONS/SERVICES OFFERED | 173 |
| TABLE 125 | STMICROELECTRONICS: PRODUCT LAUNCHES | 173 |
| TABLE 126 | STMICROELECTRONICS: DEALS | 174 |
| TABLE 127 | STMICROELECTRONICS: OTHERS | 175 |
| 13.2.2 | INFINEON TECHNOLOGIES AG | 177 |
| TABLE 128 | INFINEON TECHNOLOGIES AG: COMPANY OVERVIEW | 177 |
| FIGURE 59 | INFINEON TECHNOLOGIES AG: COMPANY SNAPSHOT | 178 |
| TABLE 129 | INFINEON TECHNOLOGIES AG: PRODUCTS/SOLUTIONS/SERVICES OFFERED | 178 |
| TABLE 130 | INFINEON TECHNOLOGIES AG: PRODUCT LAUNCHES | 179 |
| TABLE 131 | INFINEON TECHNOLOGIES AG: DEALS | 180 |
| 13.2.3 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC | 183 |
| TABLE 132 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: COMPANY OVERVIEW | 183 |
| FIGURE 60 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: COMPANY SNAPSHOT | 184 |
| TABLE 133 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: PRODUCTS/SOLUTIONS/SERVICES OFFERED | 184 |
| TABLE 134 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: PRODUCT LAUNCHES | 185 |
| TABLE 135 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: DEALS | 186 |
| TABLE 136 | SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC: OTHERS | 187 |

13.2.4 WOLFSPEED, INC. 189

TABLE 137 WOLFSPEED, INC.: COMPANY OVERVIEW 189

FIGURE 61 WOLFSPEED, INC.: COMPANY SNAPSHOT 190

TABLE 138 WOLFSPEED, INC.: PRODUCTS/SOLUTIONS/SERVICES OFFERED 190

TABLE 139 WOLFSPEED, INC.: PRODUCT LAUNCHES 191

TABLE 140 WOLFSPEED, INC.: DEALS 191

TABLE 141 WOLFSPEED, INC.: OTHERS 193

13.2.5 ROHM CO., LTD. 194

TABLE 142 ROHM CO., LTD.: COMPANY OVERVIEW 194

FIGURE 62 ROHM CO., LTD.: COMPANY SNAPSHOT 195

TABLE 143 ROHM CO., LTD.: PRODUCTS/SOLUTIONS/SERVICES OFFERED 195

TABLE 144 ROHM CO., LTD.: PRODUCT LAUNCHES 196

TABLE 145 ROHM CO., LTD.: DEALS 196

13.2.6 FUJI ELECTRIC CO., LTD. 198

TABLE 146 FUJI ELECTRIC CO., LTD.: COMPANY OVERVIEW 198

FIGURE 63 FUJI ELECTRIC CO., LTD.: COMPANY SNAPSHOT 199

TABLE 147 FUJI ELECTRIC CO., LTD.: PRODUCTS/SOLUTIONS/SERVICES OFFERED 199

TABLE 148 FUJI ELECTRIC CO., LTD.: PRODUCT LAUNCHES 200

13.2.7 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION 201

TABLE 149 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: COMPANY OVERVIEW 201

FIGURE 64 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: COMPANY SNAPSHOT 202

TABLE 150 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: PRODUCTS/SOLUTIONS/SERVICES OFFERED 202

TABLE 151 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: PRODUCT LAUNCHES 203

TABLE 152 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: DEALS 204

TABLE 153 TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION: OTHERS 205

13.2.8 MICROCHIP TECHNOLOGY INC. 206

TABLE 154 MICROCHIP TECHNOLOGY INC.: COMPANY OVERVIEW 206

FIGURE 65 MICROCHIP TECHNOLOGY INC.: COMPANY SNAPSHOT 207

TABLE 155 MICROCHIP TECHNOLOGY INC.: PRODUCTS/SOLUTIONS/SERVICES OFFERED 207

TABLE 156 MICROCHIP TECHNOLOGY INC.: PRODUCT LAUNCHES 208

TABLE 157 MICROCHIP TECHNOLOGY INC.: DEALS 209

TABLE 158 MICROCHIP TECHNOLOGY INC. OTHERS 209

13.2.9 MITSUBISHI ELECTRIC CORPORATION 210

TABLE 159 MITSUBISHI ELECTRIC CORPORATION: COMPANY OVERVIEW 210

FIGURE 66 MITSUBISHI ELECTRIC CORPORATION: COMPANY SNAPSHOT 211

TABLE 160 MITSUBISHI ELECTRIC CORPORATION: PRODUCTS/SOLUTIONS/SERVICES OFFERED 211

TABLE 161 MITSUBISHI ELECTRIC CORPORATION: PRODUCT LAUNCHES 212

TABLE 162 MITSUBISHI ELECTRIC CORPORATION: DEALS 213

13.2.10 COHERENT CORP. 214

TABLE 163 COHERENT CORP.: COMPANY OVERVIEW 214

FIGURE 67 COHERENT CORP.: COMPANY SNAPSHOT 215

TABLE 164 COHERENT CORP.: PRODUCTS/SOLUTIONS/SERVICES OFFERED 215

TABLE 165 COHERENT CORP.: DEALS 216

*Business Overview, Products/Services/Solutions Offered, MnM View, Key Strengths and Right to Win, Strategic Choices Made, Weaknesses and Competitive Threats, Recent Developments might not be captured in case of unlisted companies.

13.3 OTHER PLAYERS 217

13.3.1 HITACHI POWER SEMICONDUCTOR DEVICE, LTD. 217

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

| | | |
|---------|--|-----|
| 13.3.2 | SEMIKRON DANFOSS | 218 |
| 13.3.3 | QORVO, INC | 219 |
| 13.3.4 | GENESIC SEMICONDUCTOR INC. | 220 |
| 13.3.5 | TT ELECTRONICS | 221 |
| 13.3.6 | VISHAY INTERTECHNOLOGY, INC. | 222 |
| 13.3.7 | WEEN SEMICONDUCTORS | 223 |
| 13.3.8 | SOLITRON DEVICES, INC. | 224 |
| 13.3.9 | SANAN IC | 224 |
| 13.3.10 | BYD SEMICONDUCTOR. | 225 |
| 13.3.11 | LITTELFUSE, INC. | 226 |
| 13.3.12 | TYCO TIANRUN , INC. | 227 |
| 13.3.13 | NEXPERIA | 228 |
| 13.3.14 | INVENTCHIP TECHNOLOGY CO., LTD. | 229 |
| 13.3.15 | DIODES INCORPORATED | 230 |
| 14 | APPENDIX | 231 |
| 14.1 | INSIGHTS FROM INDUSTRY EXPERTS | 231 |
| 14.2 | DISCUSSION GUIDE | 232 |
| 14.3 | KNOWLEDGESTORE: MARKETSandMARKETS' SUBSCRIPTION PORTAL | 235 |
| 14.4 | CUSTOMIZATION OPTIONS | 237 |
| 14.5 | RELATED REPORTS | 237 |
| 14.6 | AUTHOR DETAILS | 238 |

Silicon Carbide Market by Device (SiC Discrete Device, SiC Module), Wafer Size (Up to 150mm, >150mm), End-use Application (Automotive, Energy & Power, Industrial, Transportation), Material, Crystal Structure and Region - Global Forecast to 2029

Market Report | 2024-03-21 | 233 pages | MarketsandMarkets

To place an Order with Scotts International:

- ☐ - Print this form
- ☐ - Complete the relevant blank fields and sign
- ☐ - Send as a scanned email to support@scotts-international.com

ORDER FORM:

| Select license | License | Price |
|----------------|-------------------------|------------|
| | Single User | \$4950.00 |
| | Multi User | \$6650.00 |
| | Corporate License | \$8150.00 |
| | Enterprise Site License | \$10000.00 |
| | | VAT |
| | | Total |

*Please circle the relevant license option. For any questions please contact support@scotts-international.com or 0048 603 394 346.

** VAT will be added at 23% for Polish based companies, individuals and EU based companies who are unable to provide a valid EU Vat Numbers.

| | | | |
|---------------|----------------------|-------------------------------|----------------------|
| Email* | <input type="text"/> | Phone* | <input type="text"/> |
| First Name* | <input type="text"/> | Last Name* | <input type="text"/> |
| Job title* | <input type="text"/> | | |
| Company Name* | <input type="text"/> | EU Vat / Tax ID / NIP number* | <input type="text"/> |
| Address* | <input type="text"/> | City* | <input type="text"/> |
| Zip Code* | <input type="text"/> | Country* | <input type="text"/> |

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

Date

2025-05-19

Signature



Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com